A novel Graphene transfer for flexible electronics

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In the last years, Single Layer Graphene (SLG) has been widely studied for its unique electrical and mechanical characteristics and it has been successfully exploited as a conductor or semiconductor in transistors and biosensors. High quality SLG is usually obtained by Chemical Vapor Deposition (CVD) on Cu or Ni foils and then transferred on an insulator layer. This method however lacks repeatability, it is extremely time consuming and it is hard to be scaled-up and integrated in an industrial process. In this work, a novel hot embossing approach has been developed to simplify the SLG transferring process and improve the final quality of the transferred SLG.